Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, CapSense, LCD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 16x10b Slope, 16x12b SAR; D/A 2xIDAC
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4146azi-s445

Programmable Digital Blocks

Smart I/O Block

The Smart I/O block is a fabric of switches and LUTs that allows Boolean functions to be performed in signals being routed to the pins of a GPIO port. The Smart I/O can perform logical operations on input pins to the chip and on signals going out as outputs.

Fixed Function Digital Blocks

Timer/Counter/PWM (TCPWM) Block

The TCPWM block consists of a 16-bit counter with user-programmable period length. There is a capture register to record the count value at the time of an event (which may be an I/O event), a period register that is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals that are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as dead-band programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an over-current state is indicated and the PWM driving the FETs needs to be shut off immediately with no time for software intervention. Each block also incorporates a Quadrature decoder. There are eight TCPWM blocks in PSoC 4100S Plus.

Serial Communication Block (SCB)

PSoC 4100S Plus has five serial communication blocks, which can be programmed to have SPI, I^{2}C, or UART functionality.

I^{2}C Mode: The hardware I^{2}C block implements a full multi-master and slave interface (it is capable of multi-master arbitration). This block is capable of operating at speeds of up to 400 kbps (Fast Mode) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. It also supports EZI2C that creates a mailbox address range in the memory of PSoC 4100S Plus and effectively reduces I^{2}C communication to reading from and writing to an array in memory. In addition, the block supports an 8-deep FIFO for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduces the need for clock stretching caused by the CPU not having read data on time.

The I^{2}C peripheral is compatible with the I^{2}C Standard-mode and Fast-mode devices as defined in the NXP I^{2}C-bus specification and user manual (UM10204). The I^{2}C bus I/O is implemented with GPIO in open-drain modes.

PSoC 4100S Plus is not completely compliant with the I^{2}C spec in the following respect:

- GPIO cells are not overvoltage tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I^{2}C system.

UART Mode: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

SPI Mode: The SPI mode supports full Motorola SPI, TI SSP (adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO.

CAN

There is a CAN 2.0B block with support for TT-CAN.

GPIO

PSoC 4100S Plus has up to 54 GPIOs. The GPIO block implements the following:

- Eight drive modes:
  - Analog input mode (input and output buffers disabled)
  - Input only
  - Weak pull-up with strong pull-down
  - Strong pull-up with weak pull-down
  - Open drain with strong pull-down
  - Open drain with strong pull-up
  - Strong pull-up with strong pull-down
  - Weak pull-up with weak pull-down
- Input threshold select (CMOS or LVTTL).
- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes
- Selectable slew rates for dV/dt related noise control to improve EMI

The pins are organized in logical entities called ports, which are 8-bit in width (less for Ports 5 and 6). During power-on and reset, the blocks are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin.

Data output and pin state registers store, respectively, the values to be driven on the pins and the states of the pins themselves.

Every I/O pin can generate an interrupt if so enabled and each I/O port has an interrupt request (IRQ) and interrupt service routine (ISR) vector associated with it.

Special Function Peripherals

CapSense

CapSense is supported in the PSoC 4100S Plus through a CapSense Sigma-Delta (CSD) block that can be connected to any pins through an analog multiplex bus via analog switches. CapSense function can thus be provided on any available pin or group of pins in a system under software control. A PSoC Creator component is provided for the CapSense block to make it easy for the user.

Shield voltage can be driven on another analog multiplex bus to provide water-tolerance capability. Water tolerance is provided by driving the shield electrode in phase with the sense electrode to keep the shield capacitance from attenuating the sensed input. Proximity sensing can also be implemented.

The CapSense block has two IDACs, which can be used for general purposes if CapSense is not being used (both IDACs are available in that case) or if CapSense is used without water tolerance (one IDAC is available).

The CapSense block also provides a 10-bit Slope ADC function which can be used in conjunction with the CapSense function.

The CapSense block is an advanced, low-noise, programmable block with programmable voltage references and current source ranges for improved sensitivity and flexibility. It can also use an external reference voltage. It has a full-wave CSD mode that alternates sensing to VDDA and ground to null out power-supply related noise.

LCD Segment Drive

PSoC 4100S Plus has an LCD controller, which can drive up to 4 commons and up to 50 segments. It uses full digital methods to drive the LCD segments requiring no generation of internal LCD voltages. The two methods used are referred to as Digital Correlation and PWM. Digital Correlation pertains to modulating the frequency and drive levels of the common and segment signals to generate the highest RMS voltage across a segment to light it up or to keep the RMS signal to zero. This method is good for STN displays but may result in reduced contrast with TN (cheaper) displays. PWM pertains to driving the panel with PWM signals to effectively use the capacitance of the panel to provide the integration of the modulated pulse-width to generate the desired LCD voltage. This method results in higher power consumption but can result in better results when driving TN displays. LCD operation is supported during Deep Sleep refreshing a small display buffer (4 bits; one 32-bit register per port).

Pinouts

The following table provides the pin list for PSoC 4100S Plus for the 44-pin TQFP and 64-pin TQFP Normal and Fine Pitch packages.

64-TQFP		44-TQFP	
Pin	**Name**	**Pin**	**Name**
39	P0.0	24	P0.0
40	P0.1	25	P0.1
41	P0.2	26	P0.2
42	P0.3	27	P0.3
43	P0.4	28	P0.4
44	P0.5	29	P0.5
45	P0.6	30	P0.6
46	P0.7	31	P0.7
47	XRES	32	XRES
48	VCCD	33	VCCD
49	VSSD		
50	VDDD	34	VDDD
51	P5.0		
52	P5.1		
53	P5.2		
54	P5.3		
55	P5.5		
56	VDDA	35	VDDA
57	VSSA	36	VSSA
58	P1.0	37	P1.0
59	P1.1	38	P1.1
60	P1.2	39	P1.2
61	P1.3	40	P1.3
62	P1.4	41	P1.4
63	P1.5	42	P1.5
64	P1.6	43	P1.6
1	P1.7	44	P1.7
		1	VSSD
2	P2.0	2	P2.0
3	P2.1	3	P2.1
4	P2.2	4	P2.2
5	P2.3	5	P2.3
6	P2.4	6	P2.4
7	P2.5	7	P2.5
8	P2.6	8	P2.6
9	P2.7	9	P2.7
10	VSSD	10	P6.0
11	No Connect (NC)		
12	P6.0		
13	P6.1		

Alternate Pin Functions

Each Port pin has can be assigned to one of multiple functions; it can, for example, be an analog I/O, a digital peripheral function, an LCD pin, or a CapSense pin. The pin assignments are shown in the following table.

Port/Pin	Analog	Smart I/O	ACT #0	ACT #1	ACT #3	DS #2	DS #3
P0.0	lpcomp.in_p[0]			tcpwm.tr_in[0]	scb[2].uart_cts:0	scb[2].i2c_scl:0	scb[0].spi_select1:0
P0.1	lpcomp.in_n[0]			tcpwm.tr_in[1]	scb[2].uart_rts:0	scb[2].i2c_sda:0	scb[0].spi_select2:0
P0.2	lpcomp.in_p[1]						scb[0].spi_select3:0
P0.3	lpcomp.in_n[1]						scb[2].spi_select0:1
P0.4	wco.wco_in			scb[1].uart_rx:0	scb[2].uart_rx:0	scb[1].i2c_scl:0	scb[1].spi_mosi:1
P0.5	wco.wco_out			scb[1].uart_tx:0	scb[2].uart_tx:0	scb[1].i2c_sda:0	scb[1].spi_miso:1
P0.6	exco.eco_in		srss.ext_clk:0	scb[1].uart_cts:0	scb[2].uart_tx:1		scb[1].spi_clk:1
P0.7	exco.eco_out		tcpwm.line[0]:3	scb[1].uart_rts:0			scb[1].spi_select0:1
P5.0			tcpwm.line[4]:2		scb[2].uart_rx:1	scb[2].i2c_scl:1	scb[2].spi_mosi:0
P5.1			tcpwm.line_compl[4]:2		scb[2].uart_tx:2	scb[2].i2c_sda:1	scb[2].spi_miso:0
P5.2			tcpwm.line[5]:2		scb[2].uart_cts:1	lpcomp.comp[0]:2	scb[2].spi_clk:0
P5.3			tcpwm.line_compl[5]:2		scb[2].uart_rts:1	lpcomp.comp[1]:0	scb[2].spi_select0:0
P5.4			tcpwm.line[6]:2				scb[2].spi_select1:0
P5.5			tcpwm.line_compl[6]:2				scb[2].spi_select2:0
P1.0	ctb0_oa0+	SmartIo[2].io[0]	tcpwm.line[2]:1	scb[0].uart_rx:1		scb[0].i2c_scl:0	scb[0].spi_mosi:1
P1.1	ctb0_oa0-	SmartIo[2].io[1]	tcpwm.line_compl[2]:1	scb[0].uart_tx:1		scb[0].i2c_sda:0	scb[0].spi_miso:1
P1.2	ctb0_oa0_out	SmartIo[2].io[2]	tcpwm.line[3]:1	scb[0].uart_cts:1	tcpwm.tr_in[2]	scb[2].i2c_scl:2	scb[0].spi_clk:1
P1.3	ctb0_oa1_out	SmartIo[2].io[3]	tcpwm.line_compl[3]:1	scb[0].uart_rts:1	tcpwm.tr_in[3]	scb[2].i2c_sda:2	scb[0].spi_select0:1
P1.4	ctb0_oa1-	SmartIo[2].io[4]	tcpwm.line[6]:1			scb[3].i2c_scl:0	scb[0].spi_select1:1
P1.5	ctb0_oa1+	SmartIo[2].io[5]	tcpwm.line_compl[6]:1			scb[3].i2c_sda:0	scb[0].spi_select2:1
P1.6	ctb0_oa0+	SmartIo[2].io[6]	tcpwm.line[7]:1				scb[0].spi_select3:1
P1.7	ctb0_oa1+ sar_ext_vref0 sar_ext_vref1	SmartIo[2].io[7]	tcpwm.line_compl[7]:1				scb[2].spi_clk:1
P2.0	sarmux[0]	SmartIo[0].io[0]	tcpwm.line[4]:0	csd.comp	tcpwm.tr_in[4]	scb[1].i2c_scl:1	scb[1].spi_mosi:2
P2.1	sarmux[1]	SmartIo[0].io[1]	tcpwm.line_compl[4]:0		tcpwm.tr_in[5]	scb[1].i2c_sda:1	scb[1].spi_miso:2
P2.2	sarmux[2]	SmartIo[0].io[2]	tcpwm.line[5]:1				scb[1].spi_clk:2
P2.3	sarmux[3]	SmartIo[0].io[3]	tcpwm.line_compl[5]:1				scb[1].spi_select0:2

Port/Pin	Analog	Smart I/O	ACT #0	ACT #1	ACT #3	DS #2	DS #3
P2.4	sarmux[4]	SmartIo[0].io[4]	tcpwm.line[0]:1	scb[3].uart_rx:1			scb[1].spi_select1:1
P2.5	sarmux[5]	SmartIo[0].io[5]	tcpwm.line_compl[0]:1	scb[3].uart_tx:1			scb[1].spi_select2:1
P2.6	sarmux[6]	SmartIo[0].io[6]	tcpwm.line[1]:1	scb[3].uart_cts:1			scb[1].spi_select3:1
P2.7	sarmux[7]	SmartIo[0].io[7]	tcpwm.line_compl[1]:1	scb[3].uart_rts:1		lpcomp.comp[0]:0	scb[2].spi_mosi:1
P6.0			tcpwm.line[4]:1	scb[3].uart_rx:0	can.can_tx_enb_n:0	scb[3].i2c_scl:1	scb[3].spi_mosi:0
P6.1			tcpwm.line_compl[4]:1	scb[3].uart_tx:0	can.can_rx:0	scb[3].i2c_sda:1	scb[3].spi_miso:0
P6.2			tcpwm.line[5]:0	scb[3].uart_cts:0	can.can_tx:0		scb[3].spi_clk:0
P6.3			tcpwm.line_compl[5]:0	scb[3].uart_rts:0			scb[3].spi_select0:0
P6.4			tcpwm.line[6]:0			scb[4].i2c_scl	scb[3].spi_select1:0
P6.5			tcpwm.line_compl[6]:0			scb[4].i2c_sda	scb[3].spi_select2:0
P3.0		SmartIo[1].io[0]	tcpwm.line[0]:0	scb[1].uart_rx:1		scb[1].i2c_scl:2	scb[1].spi_mosi:0
P3.1		SmartIo[1].io[1]	tcpwm.line_compl[0]:0	scb[1].uart_tx:1		scb[1].i2c_sda:2	scb[1].spi_miso:0
P3.2		SmartIo[1].io[2]	tcpwm.line[1]:0	scb[1].uart_cts:1		cpuss.swd_data	scb[1].spi_clk:0
P3.3		SmartIo[1].io[3]	tcpwm.line_compl[1]:0	scb[1].uart_rts:1		cpuss.swd_clk	scb[1].spi_select0:0
P3.4		SmartIo[1].io[4]	tcpwm.line[2]:0		tcpwm.tr_in[6]		scb[1].spi_select1:0
P3.5		SmartIo[1].io[5]	tcpwm.line_compl[2]:0				scb[1].spi_select2:0
P3.6		SmartIo[1].io[6]	tcpwm.line[3]:0			scb[4].spi_select3	scb[1].spi_select3:0
P3.7		SmartIo[1].io[7]	tcpwm.line_compl[3]:0			lpcomp.comp[1]:1	scb[2].spi_miso:1
P4.0	csd.vref_ext			scb[0].uart_rx:0	can.can_rx:1	scb[0].i2c_scl:1	scb[0].spi_mosi:0
P4.1	csd.cshield			scb[0].uart_tx:0	can.can_tx:1	scb[0].i2c_sda:1	scb[0].spi_miso:0
P4.2	csd.cmod			scb[0].uart_cts:0	can.can_tx_enb_n:1	lpcomp.comp[0]:1	scb[0].spi_clk:0
P4.3	csd.csh_tank			scb[0].uart_rts:0		lpcomp.comp[1]:2	scb[0].spi_select0:0
P4.4				scb[4].uart_rx		scb[4].spi_mosi	scb[0].spi_select1:2
P4.5				scb[4].uart_tx		scb[4].spi_miso	scb[0].spi_select2:2
P4.6				scb[4].uart_cts		scb[4].spi_clk	scb[0].spi_select3:2
P4.7				scb[4].uart_rts		scb[4].spi_select0	
P5.6			tcpwm.line[7]:0			scb[4].spi_select1	scb[2].spi_select3:0
P5.7			tcpwm.line_compl[7]:0			scb[4].spi_select2	
P7.0			tcpwm.line[0]:2	scb[3].uart_rx:2		scb[3].i2c_scl:2	scb[3].spi_mosi:1
P7.1			tcpwm.line_compl[0]:2	scb[3].uart_tx:2		scb[3].i2c_sda:2	scb[3].spi_miso:1
P7.2			tcpwm.line[1]:2	scb[3].uart_cts:2			scb[3].spi_clk:1

GPIO

Table 4. GPIO DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID57	V_{IH}[3]	Input voltage high threshold	0.7 × V_{DDD}	–	–	V	CMOS Input
SID58	V_{IL}	Input voltage low threshold	–	–	0.3 × V_{DDD}		CMOS Input
SID241	V_{IH}[3]	LVTTL input, $V_{DDD} < 2.7$ V	0.7 × V_{DDD}	–	–		–
SID242	V_{IL}	LVTTL input, $V_{DDD} < 2.7$ V	–	–	0.3 × V_{DDD}		–
SID243	V_{IH}[3]	LVTTL input, $V_{DDD} \geq 2.7$ V	2.0	–	–		–
SID244	V_{IL}	LVTTL input, $V_{DDD} \geq 2.7$ V	–	–	0.8		–
SID59	V_{OH}	Output voltage high level	V_{DDD} –0.6	–	–		I_{OH} = 4 mA at 3 V V_{DDD}
SID60	V_{OH}	Output voltage high level	V_{DDD} –0.5	–	–		I_{OH} = 1 mA at 1.8 V V_{DDD}
SID61	V_{OL}	Output voltage low level	–	–	0.6		I_{OL} = 4 mA at 1.8 V V_{DDD}
SID62	V_{OL}	Output voltage low level	–	–	0.6		I_{OL} = 10 mA at 3 V V_{DDD}
SID62A	V_{OL}	Output voltage low level	–	–	0.4		I_{OL} = 3 mA at 3 V V_{DDD}
SID63	R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	–
SID64	$R_{PULLDOWN}$	Pull-down resistor	3.5	5.6	8.5		–
SID65	I_{IL}	Input leakage current (absolute value)	–	–	2	nA	25 °C, V_{DDD} = 3.0 V
SID66	C_{IN}	Input capacitance	–	–	7	pF	–
SID67[4]	V_{HYSTTL}	Input hysteresis LVTTL	25	40	–	mV	$V_{DDD} \geq 2.7$ V
SID68[4]	$V_{HYSCMOS}$	Input hysteresis CMOS	0.05 × V_{DDD}	–	–		$V_{DD} < 4.5$ V
SID68A[4]	$V_{HYSCMOS5V5}$	Input hysteresis CMOS	200	–	–		$V_{DD} > 4.5$ V
SID69[4]	I_{DIODE}	Current through protection diode to V_{DD}/V_{SS}	–	–	100	µA	–
SID69A[4]	I_{TOT_GPIO}	Maximum total source or sink chip current	–	–	200	mA	–

Table 5. GPIO AC Specifications
(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID70	T_{RISEF}	Rise time in fast strong mode	2	–	12	ns	3.3 V V_{DDD}, Cload = 25 pF
SID71	T_{FALLF}	Fall time in fast strong mode	2	–	12		3.3 V V_{DDD}, Cload = 25 pF
SID72	T_{RISES}	Rise time in slow strong mode	10	–	60	–	3.3 V V_{DDD}, Cload = 25 pF

Notes
3. V_{IH} must not exceed V_{DDD} + 0.2 V.
4. Guaranteed by characterization.

Table 5. GPIO AC Specifications *(continued)*
(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID73	T_{FALLS}	Fall time in slow strong mode	10	–	60	–	3.3 V V_{DDD}, Cload = 25 pF
SID74	$F_{GPIOUT1}$	GPIO F_{OUT}; 3.3 V ≤ V_{DDD} ≤ 5.5 V Fast strong mode	–	–	33	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID75	$F_{GPIOUT2}$	GPIO F_{OUT}; 1.71 V≤ V_{DDD}≤ 3.3 V Fast strong mode	–	–	16.7		90/10%, 25 pF load, 60/40 duty cycle
SID76	$F_{GPIOUT3}$	GPIO F_{OUT}; 3.3 V ≤ V_{DDD} ≤ 5.5 V Slow strong mode	–	–	7		90/10%, 25 pF load, 60/40 duty cycle
SID245	$F_{GPIOUT4}$	GPIO F_{OUT}; 1.71 V ≤ V_{DDD} ≤ 3.3 V Slow strong mode.	–	–	3.5		90/10%, 25 pF load, 60/40 duty cycle
SID246	F_{GPIOIN}	GPIO input operating frequency; 1.71 V ≤ V_{DDD} ≤ 5.5 V	–	–	48		90/10% V_{IO}

XRES

Table 6. XRES DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID77	V_{IH}	Input voltage high threshold	0.7 × V_{DDD}	–	–	V	CMOS Input
SID78	V_{IL}	Input voltage low threshold	–	–	0.3 × V_{DDD}		
SID79	R_{PULLUP}	Pull-up resistor	–	60	–	kΩ	–
SID80	C_{IN}	Input capacitance	–	–	7	pF	–
SID81[5]	$V_{HYSXRES}$	Input voltage hysteresis	–	100	–	mV	Typical hysteresis is 200 mV for V_{DD} > 4.5 V
SID82	I_{DIODE}	Current through protection diode to V_{DD}/V_{SS}	–	–	100	µA	

Table 7. XRES AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID83[5]	$T_{RESETWIDTH}$	Reset pulse width	1	–	–	µs	–
BID194[5]	$T_{RESETWAKE}$	Wake-up time from reset release	–	–	2.7	ms	–

Note

[5] Guaranteed by characterization.

Analog Peripherals

CTBm Opamp

Table 8. CTBm Opamp Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
	I_{DD}	Opamp block current, External load					
SID269	I_{DD_HI}	power=hi	–	1100	1850	µA	–
SID270	I_{DD_MED}	power=med	–	550	950		–
SID271	I_{DD_LOW}	power=lo	–	150	350		–
	G_{BW}	Load = 20 pF, 0.1 mA V_{DDA} = 2.7 V					
SID272	G_{BW_HI}	power=hi	6	–	–	MHz	Input and output are 0.2 V to V_{DDA}-0.2 V
SID273	G_{BW_MED}	power=med	3	–	–		Input and output are 0.2 V to V_{DDA}-0.2 V
SID274	G_{BW_LO}	power=lo	–	1	–		Input and output are 0.2 V to V_{DDA}-0.2 V
	I_{OUT_MAX}	V_{DDA} = 2.7 V, 500 mV from rail					
SID275	$I_{OUT\_MAX\_HI}$	power=hi	10	–	–	mA	Output is 0.5 V to V_{DDA} -0.5 V
SID276	$I_{OUT\_MAX\_MID}$	power=mid	10	–	–		Output is 0.5 V to V_{DDA} -0.5 V
SID277	$I_{OUT\_MAX\_LO}$	power=lo	–	5	–		Output is 0.5 V to V_{DDA} -0.5 V
	I_{OUT}	V_{DDA} = 1.71 V, 500 mV from rail					
SID278	$I_{OUT\_MAX\_HI}$	power=hi	4	–	–	mA	Output is 0.5 V to V_{DDA} -0.5 V
SID279	$I_{OUT\_MAX\_MID}$	power=mid	4	–	–		Output is 0.5 V to V_{DDA}-0.5 V
SID280	$I_{OUT\_MAX\_LO}$	power=lo	–	2	–		Output is 0.5 V to V_{DDA}-0.5 V
	I_{DD_Int}	Opamp block current Internal Load					
SID269_I	$I_{DD\_HI\_Int}$	power=hi	–	1500	1700	µA	–
SID270_I	$I_{DD\_MED\_Int}$	power=med	–	700	900		–
SID271_I	$I_{DD\_LOW\_Int}$	power=lo	–	–	–		–
	G_{BW}	V_{DDA} = 2.7 V	–	–	–		–
SID272_I	$G_{BW\_HI\_Int}$	power=hi	8	–	–	MHz	Output is 0.25 V to V_{DDA}-0.25 V
		General opamp specs for both internal and external modes					
SID281	V_{IN}	Charge-pump on, V_{DDA} = 2.7 V	–0.05	–	V_{DDA}-0.2	V	–
SID282	V_{CM}	Charge-pump on, V_{DDA} = 2.7 V	–0.05	–	V_{DDA}-0.2		–
	V_{OUT}	V_{DDA} = 2.7 V					

Table 8. CTBm Opamp Specifications *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID283	V_{OUT_1}	power=hi, Iload=10 mA	0.5	–	V_{DDA} -0.5	V	–
SID284	V_{OUT_2}	power=hi, Iload=1 mA	0.2	–	V_{DDA} -0.2		–
SID285	V_{OUT_3}	power=med, Iload=1 mA	0.2	–	V_{DDA} -0.2		–
SID286	V_{OUT_4}	power=lo, Iload=0.1 mA	0.2	–	V_{DDA} -0.2		–
SID288	V_{OS_TR}	Offset voltage, trimmed	–1.0	±0.5	1.0	mV	High mode, input 0 V to V_{DDA}-0.2 V
SID288A	V_{OS_TR}	Offset voltage, trimmed	–	±1	–		Medium mode, input 0 V to V_{DDA}-0.2 V
SID288B	V_{OS_TR}	Offset voltage, trimmed	–	±2	–		Low mode, input 0 V to V_{DDA}-0.2 V
SID290	$V_{OS\_DR\_TR}$	Offset voltage drift, trimmed	–10	±3	10	µV/°C	High mode
SID290A	$V_{OS\_DR\_TR}$	Offset voltage drift, trimmed	–	±10	–	µV/°C	Medium mode
SID290B	$V_{OS\_DR\_TR}$	Offset voltage drift, trimmed	–	±10	–		Low mode
SID291	CMRR	DC	70	80	–	dB	Input is 0 V to V_{DDA}-0.2 V, Output is 0.2 V to V_{DDA}-0.2 V
SID292	PSRR	At 1 kHz, 10-mV ripple	70	85	–		V_{DDD} = 3.6 V, high-power mode, input is 0.2 V to V_{DDA}-0.2 V
	Noise						
SID294	VN2	Input-referred, 1 kHz, power = Hi	–	72	–	nV/rtHz	Input and output are at 0.2 V to V_{DDA}-0.2 V
SID295	VN3	Input-referred, 10 kHz, power = Hi	–	28	–		Input and output are at 0.2 V to V_{DDA}-0.2 V
SID296	VN4	Input-referred, 100 kHz, power = Hi	–	15	–		Input and output are at 0.2 V to V_{DDA}-0.2 V
SID297	C_{LOAD}	Stable up to max. load. Performance specs at 50 pF.	–	–	125	pF	–
SID298	SLEW_RATE	Cload = 50 pF, Power = High, V_{DDA} = 2.7 V	6	–	–	V/µs	–
SID299	T_OP_WAKE	From disable to enable, no external RC dominating	–	–	25	µs	–
SID299A	OL_GAIN	Open Loop Gain	–	90	–	dB	
	COMP_MODE	Comparator mode; 50 mV drive, T_{rise}=T_{fall} (approx.)					

Table 8. CTBm Opamp Specifications *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID300	TPD1	Response time; power=hi	–	150	–	ns	Input is 0.2 V to V_{DDA}-0.2 V
SID301	TPD2	Response time; power=med	–	500	–		Input is 0.2 V to V_{DDA}-0.2 V
SID302	TPD3	Response time; power=lo	–	2500	–		Input is 0.2 V to V_{DDA}-0.2 V
SID303	VHYST_OP	Hysteresis	–	10	–	mV	–
SID304	WUP_CTB	Wake-up time from Enabled to Usable	–	–	25	µs	–
	Deep Sleep Mode	Mode 2 is lowest current range. Mode 1 has higher GBW.					
SID_DS_1	$I_{DD\_HI\_M1}$	Mode 1, High current	–	1400	–	µA	25 °C
SID_DS_2	$I_{DD\_MED\_M1}$	Mode 1, Medium current	–	700	–		25 °C
SID_DS_3	$I_{DD\_LOW\_M1}$	Mode 1, Low current	–	200	–		25 °C
SID_DS_4	$I_{DD\_HI\_M2}$	Mode 2, High current	–	120	–		25 °C
SID_DS_5	$I_{DD\_MED\_M2}$	Mode 2, Medium current	–	60	–		25 °C
SID_DS_6	$I_{DD\_LOW\_M2}$	Mode 2, Low current	–	15	–		25 °C
SID_DS_7	$G_{BW\_HI\_M1}$	Mode 1, High current	–	4	–	MHz	20-pF load, no DC load 0.2 V to V_{DDA}-0.2 V
SID_DS_8	$G_{BW\_MED\_M1}$	Mode 1, Medium current	–	2	–		20-pF load, no DC load 0.2 V to V_{DDA}-0.2 V
SID_DS_9	$G_{BW\_LOW\_M1}$	Mode 1, Low current	–	0.5	–		20-pF load, no DC load 0.2 V to V_{DDA}-0.2 V
SID_DS_10	$G_{BW\_HI\_M2}$	Mode 2, High current	–	0.5	–		20-pF load, no DC load 0.2 V to V_{DDA}-0.2 V
SID_DS_11	$G_{BW\_MED\_M2}$	Mode 2, Medium current	–	0.2	–		20-pF load, no DC load 0.2 V to V_{DDA}-0.2 V
SID_DS_12	$G_{BW\_Low\_M2}$	Mode 2, Low current	–	0.1	–		20-pF load, no DC load 0.2 V to V_{DDA}-0.2 V
SID_DS_13	$V_{OS\_HI\_M1}$	Mode 1, High current	–	5	–	mV	With trim 25 °C, 0.2 V to V_{DDA}-0.2 V
SID_DS_14	$V_{OS\_MED\_M1}$	Mode 1, Medium current	–	5	–		With trim 25 °C, 0.2 V to V_{DDA}-0.2 V
SID_DS_15	$V_{OS\_LOW\_M2}$	Mode 1, Low current	–	5	–		With trim 25 °C, 0.2 V to V_{DDA}-0.2 V
SID_DS_16	$V_{OS\_HI\_M2}$	Mode 2, High current	–	5	–		With trim 25 °C, 0.2V to V_{DDA}-0.2 V
SID_DS_17	$V_{OS\_MED\_M2}$	Mode 2, Medium current	–	5	–		With trim 25 °C, 0.2 V to V_{DDA}-0.2 V
SID_DS_18	$V_{OS\_LOW\_M2}$	Mode 2, Low current	–	5	–		With trim 25 °C, 0.2 V to V_{DDA}-0.2 V

Table 8. CTBm Opamp Specifications *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID_DS_19	$I_{OUT\_HI\_M1}$	Mode 1, High current	–	10	–	mA	Output is 0.5 V to V_{DDA}-0.5 V
SID_DS_20	$I_{OUT\_MED\_M1}$	Mode 1, Medium current	–	10	–		Output is 0.5 V to V_{DDA}-0.5 V
SID_DS_21	$I_{OUT\_LOW\_M1}$	Mode 1, Low current	–	4	–		Output is 0.5 V to V_{DDA}-0.5 V
SID_DS_22	$I_{OUT\_HI\_M2}$	Mode 2, High current	–	1	–		
SID_DS_23	$I_{OU\_MED\_M2}$	Mode 2, Medium current	–	1	–		
SID_DS_24	$I_{OU\_LOW\_M2}$	Mode 2, Low current	–	0.5	–		

Comparator

Table 9. Comparator DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID84	$V_{OFFSET1}$	Input offset voltage, Factory trim	–	–	±10	mV	
SID85	$V_{OFFSET2}$	Input offset voltage, Custom trim	–	–	±4		
SID86	V_{HYST}	Hysteresis when enabled	–	10	35		
SID87	V_{ICM1}	Input common mode voltage in normal mode	0	–	V_{DDD}-0.1	V	Modes 1 and 2
SID247	V_{ICM2}	Input common mode voltage in low power mode	0	–	V_{DDD}		
SID247A	V_{ICM3}	Input common mode voltage in ultra low power mode	0	–	V_{DDD}-1.15		$V_{DDD} \geq 2.2$ V at –40 °C
SID88	C_{MRR}	Common mode rejection ratio	50	–	–	dB	$V_{DDD} \geq 2.7$V
SID88A	C_{MRR}	Common mode rejection ratio	42	–	–		$V_{DDD} \leq 2.7$V
SID89	I_{CMP1}	Block current, normal mode	–	–	400	µA	
SID248	I_{CMP2}	Block current, low power mode	–	–	100		
SID259	I_{CMP3}	Block current in ultra low-power mode	–	–	6		$V_{DDD} \geq 2.2$ V at –40 °C
SID90	Z_{CMP}	DC Input impedance of comparator	35	–	–	MΩ	

Table 10. Comparator AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID91	TRESP1	Response time, normal mode, 50 mV overdrive	–	38	110	ns	
SID258	TRESP2	Response time, low power mode, 50 mV overdrive	–	70	200		
SID92	TRESP3	Response time, ultra-low power mode, 200 mV overdrive	–	2.3	15	µs	$V_{DDD} \geq 2.2$ V at –40 °C

Note

6. Guaranteed by characterization.

Temperature Sensor

Table 11. Temperature Sensor Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID93	TSENSACC	Temperature sensor accuracy	–5	±1	5	°C	–40 to +85 °C

SAR ADC

Table 12. SAR ADC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SAR ADC DC Specifications							
SID94	A_RES	Resolution	–	–	12	bits	
SID95	A_CHNLS_S	Number of channels - single ended	–	–	16		
SID96	A-CHNKS_D	Number of channels - differential	–	–	4		Diff inputs use neighboring I/O
SID97	A-MONO	Monotonicity	–	–	–		Yes
SID98	A_GAINERR	Gain error	–	–	±0.1	%	With external reference
SID99	A_OFFSET	Input offset voltage	–	–	2	mV	Measured with 1-V reference
SID100	A_ISAR	Current consumption	–	–	1	mA	
SID101	A_VINS	Input voltage range - single ended	V_{SS}	–	V_{DDA}	V	
SID102	A_VIND	Input voltage range - differential	V_{SS}	–	V_{DDA}	V	
SID103	A_INRES	Input resistance	–	–	2.2	KΩ	
SID104	A_INCAP	Input capacitance	–	–	10	pF	
SID260	VREFSAR	Trimmed internal reference to SAR	–	–	TBD	V	
SAR ADC AC Specifications							
SID106	A_PSRR	Power supply rejection ratio	70	–	–	dB	
SID107	A_CMRR	Common mode rejection ratio	66	–	–	dB	Measured at 1 V
SID108	A_SAMP	Sample rate	–	–	1	Msps	
SID109	A_SNR	Signal-to-noise and distortion ratio (SINAD)	65	–	–	dB	F_{IN} = 10 kHz
SID110	A_BW	Input bandwidth without aliasing	–	–	A_samp/2	kHz	
SID111	A_INL	Integral non linearity. V_{DD} = 1.71 to 5.5, 1 Msps	–1.7	–	2	LSB	V_{REF} = 1 to V_{DD}
SID111A	A_INL	Integral non linearity. V_{DDD} = 1.71 to 3.6, 1 Msps	–1.5	–	1.7	LSB	V_{REF} = 1.71 to V_{DD}
SID111B	A_INL	Integral non linearity. V_{DD} = 1.71 to 5.5, 500 ksps	–1.5	–	1.7	LSB	V_{REF} = 1 to V_{DD}
SID112	A_DNL	Differential non linearity. V_{DD} = 1.71 to 5.5, 1 Msps	–1	–	2.2	LSB	V_{REF} = 1 to V_{DD}
SID112A	A_DNL	Differential non linearity. V_{DD} = 1.71 to 3.6, 1 Msps	–1	–	2	LSB	V_{REF} = 1.71 to V_{DD}
SID112B	A_DNL	Differential non linearity. V_{DD} = 1.71 to 5.5, 500 ksps	–1	–	2.2	LSB	V_{REF} = 1 to V_{DD}
SID113	A_THD	Total harmonic distortion	–	–	–65	dB	Fin = 10 kHz
SID261	FSARINTREF	SAR operating speed without external reference bypass	–	–	100	ksps	12-bit resolution

CSD and IDAC

Table 13. CSD and IDAC Specifications

SPEC ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SYS.PER#3	VDD_RIPPLE	Max allowed ripple on power supply, DC to 10 MHz	–	–	±50	mV	V_{DD} > 2 V (with ripple), 25 °C T_A, Sensitivity = 0.1 pF
SYS.PER#16	VDD_RIPPLE_1.8	Max allowed ripple on power supply, DC to 10 MHz	–	–	±25	mV	V_{DD} > 1.75V (with ripple), 25 °C T_A, Parasitic Capacitance (C_P) < 20 pF, Sensitivity ≥ 0.4 pF
SID.CSD.BLK	ICSD	Maximum block current	–	–	4000	µA	Maximum block current for both IDACs in dynamic (switching) mode including comparators, buffer, and reference generator
SID.CSD#15	V_{REF}	Voltage reference for CSD and Comparator	0.6	1.2	V_{DDA} - 0.6	V	V_{DDA} - 0.06 or 4.4, whichever is lower
SID.CSD#15A	VREF_EXT	External Voltage reference for CSD and Comparator	0.6		V_{DDA} - 0.6	V	V_{DDA} - 0.06 or 4.4, whichever is lower
SID.CSD#16	IDAC1IDD	IDAC1 (7-bits) block current	–	–	1750	µA	
SID.CSD#17	IDAC2IDD	IDAC2 (7-bits) block current	–	–	1750	µA	
SID308	VCSD	Voltage range of operation	1.71	–	5.5	V	1.8 V ±5% or 1.8 V to 5.5 V
SID308A	VCOMPIDAC	Voltage compliance range of IDAC	0.6	–	V_{DDA} –0.6	V	V_{DDA} - 0.06 or 4.4, whichever is lower
SID309	IDAC1DNL	DNL	–1	–	1	LSB	
SID310	IDAC1INL	INL	–2	–	2	LSB	INL is ±5.5 LSB for V_{DDA} < 2 V
SID311	IDAC2DNL	DNL	–1	–	1	LSB	
SID312	IDAC2INL	INL	–2	–	2	LSB	INL is ±5.5 LSB for V_{DDA} < 2 V
SID313	SNR	Ratio of counts of finger to noise. Guaranteed by characterization	5	–	–	Ratio	Capacitance range of 5 to 35 pF, 0.1-pF sensitivity. All use cases. V_{DDA} > 2 V.
SID314	IDAC1CRT1	Output current of IDAC1 (7 bits) in low range	4.2	–	5.4	µA	LSB = 37.5-nA typ
SID314A	IDAC1CRT2	Output current of IDAC1(7 bits) in medium range	34	–	41	µA	LSB = 300-nA typ
SID314B	IDAC1CRT3	Output current of IDAC1(7 bits) in high range	275	–	330	µA	LSB = 2.4-µA typ
SID314C	IDAC1CRT12	Output current of IDAC1 (7 bits) in low range, 2X mode	8	–	10.5	µA	LSB = 75-nA typ
SID314D	IDAC1CRT22	Output current of IDAC1(7 bits) in medium range, 2X mode	69	–	82	µA	LSB = 600-nA typ.
SID314E	IDAC1CRT32	Output current of IDAC1(7 bits) in high range, 2X mode	540	–	660	µA	LSB = 4.8-µA typ
SID315	IDAC2CRT1	Output current of IDAC2 (7 bits) in low range	4.2	–	5.4	µA	LSB = 37.5-nA typ
SID315A	IDAC2CRT2	Output current of IDAC2 (7 bits) in medium range	34	–	41	µA	LSB = 300-nA typ
SID315B	IDAC2CRT3	Output current of IDAC2 (7 bits) in high range	275	–	330	µA	LSB = 2.4-µA typ
SID315C	IDAC2CRT12	Output current of IDAC2 (7 bits) in low range, 2X mode	8	–	10.5	µA	LSB = 75-nA typ
SID315D	IDAC2CRT22	Output current of IDAC2(7 bits) in medium range, 2X mode	69	–	82	µA	LSB = 600-nA typ
SID315E	IDAC2CRT32	Output current of IDAC2(7 bits) in high range, 2X mode	540	–	660	µA	LSB = 4.8-µA typ
SID315F	IDAC3CRT13	Output current of IDAC in 8-bit mode in low range	8	–	10.5	µA	LSB = 37.5-nA typ

Table 13. CSD and IDAC Specifications *(continued)*

SPEC ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID315G	IDAC3CRT23	Output current of IDAC in 8-bit mode in medium range	69	–	82	µA	LSB = 300-nA typ
SID315H	IDAC3CRT33	Output current of IDAC in 8-bit mode in high range	540	–	660	µA	LSB = 2.4-µA typ
SID320	IDACOFFSET	All zeroes input	–	–	1	LSB	Polarity set by Source or Sink. Offset is 2 LSBs for 37.5 nA/LSB mode
SID321	IDACGAIN	Full-scale error less offset	–	–	±10	%	
SID322	IDACMISMATCH1	Mismatch between IDAC1 and IDAC2 in Low mode	–	–	9.2	LSB	LSB = 37.5-nA typ
SID322A	IDACMISMATCH2	Mismatch between IDAC1 and IDAC2 in Medium mode	–	–	5.6	LSB	LSB = 300-nA typ
SID322B	IDACMISMATCH3	Mismatch between IDAC1 and IDAC2 in High mode	–	–	6.8	LSB	LSB = 2.4-µA typ
SID323	IDACSET8	Settling time to 0.5 LSB for 8-bit IDAC	–	–	5	µs	Full-scale transition. No external load
SID324	IDACSET7	Settling time to 0.5 LSB for 7-bit IDAC	–	–	5	µs	Full-scale transition. No external load
SID325	CMOD	External modulator capacitor.	–	2.2	–	nF	5-V rating, X7R or NP0 cap

10-bit CapSense ADC

Table 14. 10-bit CapSense ADC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SIDA94	A_RES	Resolution	–	–	10	bits	Auto-zeroing is required every millisecond
SIDA95	A_CHNLS_S	Number of channels - single ended	–	–	16		Defined by AMUX Bus
SIDA97	A-MONO	Monotonicity	–	–	–	Yes	
SIDA98	A_GAINERR	Gain error	–	–	±3	%	In V_{REF} (2.4 V) mode with V_{DDA} bypass capacitance of 10 µF
SIDA99	A_OFFSET	Input offset voltage	–	–	±18	mV	In V_{REF} (2.4 V) mode with V_{DDA} bypass capacitance of 10 µF
SIDA100	A_ISAR	Current consumption	–	–	0.25	mA	
SIDA101	A_VINS	Input voltage range - single ended	V_{SSA}	–	V_{DDA}	V	
SIDA103	A_INRES	Input resistance	–	2.2	–	KΩ	
SIDA104	A_INCAP	Input capacitance	–	20	–	pF	
SIDA106	A_PSRR	Power supply rejection ratio	–	60	–	dB	In V_{REF} (2.4 V) mode with V_{DDA} bypass capacitance of 10 µF
SIDA107	A_TACQ	Sample acquisition time	–	1	–	µs	
SIDA108	A_CONV8	Conversion time for 8-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.	–	–	21.3	µs	Does not include acquisition time. Equivalent to 44.8 ksps including acquisition time.
SIDA108A	A_CONV10	Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.	–	–	85.3	µs	Does not include acquisition time. Equivalent to 11.6 ksps including acquisition time.

SPI

Table 18. SPI DC Specifications[8]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID163	ISPI1	Block current consumption at 1 Mbps	–	–	360	µA	–
SID164	ISPI2	Block current consumption at 4 Mbps	–	–	560		–
SID165	ISPI3	Block current consumption at 8 Mbps	–	–	600		–

Table 19. SPI AC Specifications[8]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID166	FSPI	SPI Operating frequency (Master; 6X Oversampling)	–	–	8	MHz	
Fixed SPI Master Mode AC Specifications							
SID167	TDMO	MOSI Valid after SClock driving edge	–	–	15	ns	–
SID168	TDSI	MISO Valid before SClock capturing edge	20	–	–		Full clock, late MISO sampling
SID169	THMO	Previous MOSI data hold time	0	–	–		Referred to Slave capturing edge
Fixed SPI Slave Mode AC Specifications							
SID170	TDMI	MOSI Valid before Sclock Capturing edge	40	–	–	ns	–
SID171	TDSO	MISO Valid after Sclock driving edge	–	–	42 + 3*Tcpu		$T_{CPU} = 1/F_{CPU}$
SID171A	TDSO_EXT	MISO Valid after Sclock driving edge in Ext. Clk mode	–	–	48		–
SID172	THSO	Previous MISO data hold time	0	–	–		–
SID172A	TSSELSSCK	SSEL Valid to first SCK Valid edge	–	–	100	ns	–

UART

Table 20. UART DC Specifications[8]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID160	I_{UART1}	Block current consumption at 100 Kbps	–	–	55	µA	–
SID161	I_{UART2}	Block current consumption at 1000 Kbps	–	–	312	µA	–

Table 21. UART AC Specifications[8]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID162	F_{UART}	Bit rate	–	–	1	Mbps	–

Note

[8] Guaranteed by characterization.

Watch Crystal Oscillator (WCO)

Table 33. WCO Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID398	FWCO	Crystal frequency	–	32.768	–	kHz	
SID399	FTOL	Frequency tolerance	–	50	250	ppm	With 20-ppm crystal
SID400	ESR	Equivalent series resistance	–	50	–	kΩ	
SID401	PD	Drive Level	–	–	1	µW	
SID402	TSTART	Startup time	–	–	500	ms	
SID403	CL	Crystal Load Capacitance	6	–	12.5	pF	
SID404	C0	Crystal Shunt Capacitance	–	1.35	–	pF	
SID405	IWCO1	Operating Current (high power mode)	–	–	8	uA	

External Clock

Table 34. External Clock Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID305[13]	ExtClkFreq	External clock input frequency	0	–	48	MHz	–
SID306[13]	ExtClkDuty	Duty cycle; measured at $V_{DD/2}$	45	–	55	%	–

External Crystal Oscillator and PLL

Table 35. External Crystal Oscillator (ECO) Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID316[13]	IECO1	External clock input frequency	–	–	1.5	mA	–
SID317[13]	FECO	Crystal frequency range	4	–	33	MHz	–

Table 36. PLL Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID410	IDD_PLL_48	In = 3 MHz, Out = 48 MHz	–	530	610	uA	
SID411	IDD_PLL_24	In = 3 MHz, Out = 24 MHz	–	300	405	uA	
SID412	Fpllin	PLL input frequency	1	–	48	MHz	
SID413	Fpllint	PLL intermediate frequency; prescaler out	1	–	3	MHz	
SID414	Fpllvco	VCO output frequency before post-divide	22.5	–	104	MHz	
SID415	Divvco	VCO Output post-divider range; PLL output frequency is Fpplvco/Divvco	1	–	8		
SID416	Plllocktime	Lock time at startup	–	–	250	µs	
SID417	Jperiod_1	Period jitter for VCO ≥ 67 MHz	–	–	150	ps	Guaranteed by design
SID416A	Jperiod_2	Period jitter for VCO ≤ 67 MHz	–	–	200	ps	Guaranteed by design

System Clock

Table 37. Block Specs

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID262[13]	$T_{CLKSWITCH}$	System clock source switching time	3	–	4	Periods	–

Note

[13] Guaranteed by characterization.

Packaging

The PSoC 4100S Plus will be offered in 44 TQFP, 64 TQFP Normal pitch, and 64 TQFP Fine Pitch packages.

Package dimensions and Cypress drawing numbers are in the following table.

Table 40. Package List

Spec ID#	Package	Description	Package Dwg
BID20	64-pin TQFP	14 × 14 × 1.4-mm height with 0.8-mm pitch	51-85046
BID27	64-pin TQFP	10 × 10 × 1.6-mm height with 0.5-mm pitch	51-85051
BID34A	44-pin TQFP	10 × 10 × 1.4-mm height with 0.8-mm pitch	51-85064

Table 41. Package Thermal Characteristics

Parameter	Description	Package	Min	Typ	Max	Units
T_A	Operating ambient temperature		–40	25	85	°C
T_J	Operating junction temperature		–40	–	100	°C
T_{JA}	Package θ_{JA}	44-pin TQFP	–	55.6	–	°C/Watt
T_{JC}	Package θ_{JC}	44-pin TQFP	–	14.4	–	°C/Watt
T_{JA}	Package θ_{JA}	64-pin TQFP (0.5-mm pitch)	–	46	–	°C/Watt
T_{JC}	Package θ_{JC}	64-pin TQFP (0.5-mm pitch)	–	10	–	°C/Watt
T_{JA}	Package θ_{JA}	64-pin TQFP (0.8-mm pitch)	–	36.8	–	°C/Watt
T_{JC}	Package θ_{JC}	64-pin TQFP (0.8-mm pitch)	–	9.4	–	°C/Watt

Table 42. Solder Reflow Peak Temperature

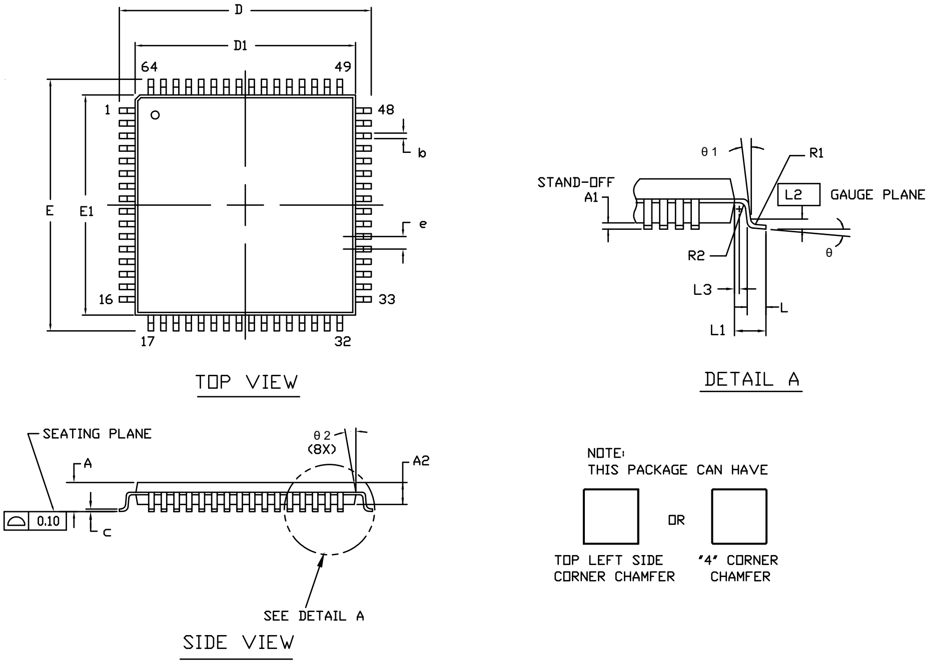
Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
All	260 °C	30 seconds

Table 43. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-020

Package	MSL
All	MSL 3

Package Diagrams

Figure 7. 64-pin TQFP Package (0.8-mm Pitch) Outline



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	1.60
A1	0.05	—	0.15
A2	1.35	1.40	1.45
D	15.75	16.00	16.25
D1	13.95	14.00	14.05
E	15.75	16.00	16.25
E1	13.95	14.00	14.05
R1	0.08	—	0.20
R2	0.08	—	0.20
θ	0°	—	7°
θ1	0°	—	—
θ2	11°	12°	13°
c	—	—	0.20
b	0.30	0.35	0.40
L	0.45	0.60	0.75
L1	1.00 REF		
L2	0.25 BSC		
L3	0.20	—	—
e	0.80 TYP		

NOTE:

1. JEDEC STD REF MS-026
2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.0098 in (0.25 mm) PER SIDE BODY LENGTH DIMENSIONS ARE MAX PLASTIC BODY SIZE INCLUDING MOLD MISMATCH
3. DIMENSIONS IN MILLIMETERS

51-85046 *H

Revision History

Description Title: PSoC® 4: PSoC 4100S Plus Datasheet Programmable System-on-Chip (PSoC) Document Number: 002-19966				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
*E	5995731	WKA	12/15/2017	New release
*F	6069640	JIAO	02/13/2018	Updated Pinouts and DC Specifications.
*G	6169676	WKA	05/09/2018	Updated Clock Diagram to show Watchdog details and clock divider information. Removed preliminary statement in Pinouts.

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